



08921250

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: **Yasunori INOUE et al.**

Serial Number: **Not Yet Assigned**

Filed: **August 29, 1997**

For: **FABRICATION METHOD OF SEMICONDUCTOR DEVICE AND ABRASIVE LIQUID USED THEREIN**

**CLAIM FOR PRIORITY UNDER 35 U.S.C. 119**

Assistant Commissioner for Patents  
Washington, D.C. 20231

August 29, 1997

Sir:

The benefit of the filing dates of the following prior foreign applications are hereby requested for the above-identified application, and the priority provided in 35 U.S.C. 119 is hereby claimed:

**Japanese Appln. No. 8-230826, filed on August 30, 1996; and**

**Japanese Appln. No. 9-010426, filed on January 23, 1997.**

In support of this claim, the requisite certified copies of said original foreign applications are filed herewith.

It is requested that the file of this application be marked to indicate that the applicants have complied with the requirements of 35 U.S.C. 119 and that the Patent and Trademark Office kindly acknowledge receipt of said documents.

In the event that any fees are due in connection with this paper, please charge our Deposit Account No. 01-2340.

Respectfully submitted,  
**ARMSTRONG, WESTERMAN, HATTORI  
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日本国特許庁  
PATENT OFFICE  
JAPANESE GOVERNMENT

別紙添付の書類に記載されている事項は下記の出願書類に記載されて  
る事項と同一であることを証明する。

This is to certify that the annexed is a true copy of the following application as filed  
in this Office.

出願年月日  
Date of Application:

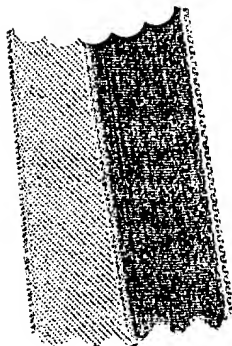
1996年 8月30日  
August 30, 1996

願番号  
Application Number:

平成 8年特許願第230826号  
Pat. Appln. No. 8-230826

願人  
Applicant(s):

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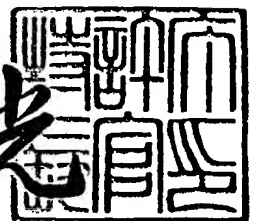


1997年 5月30日  
May 30, 1997

特許庁長官  
Commissioner,  
Patent Office

荒井 寿光

Hisamitsu ARAI



出証番号 出証特平09-3039955

Shutsu-sho-No. Shutsu-sho-toku-hei 09-3039955